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Wednesday, September 27, 2017

Registration

🕒 8.00 am – 9.00 am

Welcome

🕒 9.00 am – 9.15 am

Keynote 1:

Power Electronics Research in the European ECPE Network –
High Power Density System Integration

Thomas Harder, ECPE European Center for Power Electronics e.V.

Chair: John Janssen, NXP Semiconductors

🕒 9.15 am – 10.00 am

→ Session 2:

Power Electronics

🕒 12.00 pm – 1.00 pm

→ Session 3:

Thermal Measurement I

🕒 2.10 pm – 3.30 pm

→ Session 4:

Model Order Reduction and Compact Models

🕒 4.00 pm – 5.20 pm

→ Poster Introduction 1

🕒 5.20 pm – 6.10 pm

→ Poster Viewing Session & Cocktails

🕒 6.10 pm – 8.15 pm

→ Session 1:

Modelling and Simulation I

🕒 10.00 am – 11.00 am

Vendor Session

🕒 11.00 am – 11.30 am

Wednesday, September 27, 2017

🕒 10.00 am – 1.00 pm

Session 1:

Modelling and Simulation I

🕒 10.00 am – 11.00 am

→ Chair: John Janssen, NXP Semiconductors

Session 2:

Power Electronics

🕒 12.00 pm – 1.00 pm

→ Chair: Thomas Harder, ECPE European Center for Power Electronics e.V.

10.00 am Co-Design, Modelling and Simulation Challenges: From Components to Systems.....1

Chris Bailey¹, John Parry²

¹University of Greenwich, United Kingdom;

²Mentor, A Siemens Business, United Kingdom

10.20 am A Multi-Objective Genetic Algorithm Optimization of Plate-Fin Heatsinks.....5

Younis O. Abdelsalam, Sajad Alimohammadi,

Quentin Pelletier, Tim Persoons

Trinity College, the University of Dublin, Ireland

10.40 am Design of Experiments in Thermal Architecture.....11

Wendy Luiten

WLC, The Netherlands

Vendor Session

🕒 11.00 am – 11.30 am

12.00 pm A Simple Metal-Semiconductor Substructure for the Advanced Thermo-Mechanical Numerical Modeling of the of Power Integrated Circuits.....18

Ioan Adrian Bojita¹, Cristian Mihai Boianceanu²,

Ioan Marius Purcar¹, Cosmin-Sorin Plesa¹

¹Technical University of Cluj-Napoca, Romania;

²Infineon Technologies, Romania

12.20 pm Thermal Characterisation of a Copper Clip Bonded IGBT Module with Double-sided Cooling.....24

Qingwei Zhu¹, Andrew Forsyth¹, Rebecca Todd¹, Liam Mills²

¹School of Electrical and Electronic Engineering, University

of Manchester, United Kingdom; ²TT Electronics Semelab

12.40 pm Thermal Performance Improvement of an Air-cooled GaN-based Solid State Power Amplifier.....30

Canberk Oztoprak^{1,2}, Eser Erkek¹

¹Aselsan A.Ş., Ankara, Turkey; ²Middle East Technical University,

Ankara, Turkey

Session 3:
Thermal Measurement I

🕒 2.10 pm – 3.30 pm

Wednesday, September 27, 2017

🕒 2.10 pm – 3.30 pm

➔ Chair: Gabor Farkas, Mentor, A Siemens Business

2.10 pm Modelling and Characterisation of a Grease Pump-Out Test Stand and its Use for Accelerated Stress Testing of Thermal Greases.....36

Bernhard Wunderle¹, Jens Heilmann¹, Daniel May¹, Jörg Arnold¹, Josef Hirscheider¹, Jörg Bauer⁴, Ralph Schacht², Jürgen Vogel³, Mohamad Abo Ras³

¹TU Chemnitz, Germany; ²BTU Cottbus, Germany; ³Nanotest, Berlin, Germany; ⁴Fraunhofer IZM, Berlin, Germany; ⁵University of Applied Sciences, Zwickau, Germany

2.30 pm Development, Design and Fabrication of a Measurement Chip for Thermal Material Characterization Based on the 3-Omega Method.....42

Corinna Grosse¹, Mohamad Abo Ras¹, Aapo Varpula², Kestutis Grigoras², Daniel May^{1,3}, Mika Prunnila², Bernhard Wunderle³, Séverine Gomès⁴

¹Berliner Nanotest und Design GmbH, Germany; ²VTT Technical Research Centre of Finland Ltd, Finland; ³Technische Universität Chemnitz, Germany; ⁴Université de Lyon, CNRS, INSA de Lyon, CETHIL, France

2.50 pm Microelectronics Thin Films and Boundaries Characterized by Local Electro-thermal Measurements.....47

Axel Pic^{1,2}, Sébastien Gallois-Garreignot², Vincent Fiori², P-Olivier Chapuis¹

¹CETHIL, CNRS - INSA Lyon, France; ²ST Microelectronics, Crolles, France

3.10 pm Effect of Forward Voltage Change Depending on Gate Voltage in Body Diode of SiC-MOSFET at Thermal Transient Testing for Analysing SiC Power Module Package.....53

Fumiki Kato¹, Hidekazu Tanisawa^{1,2}, Kenichi Kouji^{1,3}, Shinji Sato¹, Toru Aoki^{1,3}, Yoshinori Murakami^{1,4}, Hiroshi Nakagawa¹, Hiroshi Yamaguchi¹, Hiroshi Sato¹

¹National Institute of Advanced Industrial Science and Technology, Japan;

²Sanken Electric Co., Ltd, Japan; ³Calsonic Kansei Corporation; ⁴Nissan Motor Co Ltd, Japan

Wednesday, September 27, 2017

🕒 4.00 pm – 5.20 pm

Session 4:
Model Order Reduction and Compact Models

🕒 4.00 pm – 5.20 pm

➔ Chair: John Janssen, NXP Semiconductors

4.00 pm Connecting MOR-based Boundary Condition Independent Compact Thermal Models.....57

Lorenzo Codecasa¹, Robin Bornoff², James Dyson², Vincenzo d'Alessandro³, Alessandro Magnani³, Niccolò Rinaldi³

¹Politecnico di Milano, Italy; ²Mentor, A Siemens Business, United Kingdom; ³Università Federico II, Italy

4.20 pm Numerical Analysis of 3D Model Order Reduction Based on Second-Order Dual-Phase-Lag Heat Transfer Equation.....62

Tomasz Raszkowski, Agnieszka Samson, Mariusz Zubert, Marcin Janicki, Andrzej Napieralski

Lodz University of Technology, Poland

4.40 pm Delphi-like Compact Thermal Models using Model Order Reduction.....68

Brice Rogie^{1,2}, Lorenzo Codecasa³, Eric Monier-Vinard³, Valentin Bissuel², Olivier Daniel², Dario D'Amore³, Alessandro Magnani³, Vincenzo d'Alessandro⁴, Niccolò Rinaldi⁴, Najib Laraqi¹

¹Université Paris Ouest, France; ²Thales Global Services, France;

³Politecnico di Milano, Italy; ⁴University Federico II, Italy

5.00 pm Novel Approach for the Extraction of Nonlinear Compact Thermal Models.....74

Lorenzo Codecasa¹, Vincenzo d'Alessandro², Alessandro Magnani², Niccolò Rinaldi²

¹Politecnico di Milano, Italy; ²Università Federico II, Italy

Poster Introduction 1

🕒 5.20 pm – 6.10 pm

➔ Chair: Marta Rencz, Budapest University of Technology & Economics

- 01 A Study on Thermal Behaviour Prediction for Automotive Electronic Unit based on CFD.....80**
Chang-Kyu Han¹, Hun Jung²
¹LS Automotive Corp., Republic of South Korea; ²LS Automotive Corp., Republic of South Korea
- 02 A Study on the Measurement of Transient Thermal Characteristics for Multi-Layered Ceramic Substrate.....84**
Shuhei Fukunaga, Tsuyoshi Funaki
Osaka University, Japan
- 03 Electrical-Thermal-Structural Performances of Packaged Power Terminals for Wafer Baking.....88**
Kyoung Joon Kim, Dae Seong Woo
Pukyong National University, Republic of South Korea
- 04 Hydrodynamics Behaviour Study of a DCJ System on the Thermal Cooling of Electronic Casings.....91**
Jean-Pierre Fradin, Andreas Rumpf, Claudia Cadile, Dominique Elzo
Icam, France
- 05 Cold Sprayed Boiling Enhancement Coating.....95**
Thomas L. Lupton, Rocco Lupoi, Anthony Robinson
Trinity College Dublin, Ireland

- 06 Comparison of Two Alternate Junction Temperature Setting Methods aimed for Thermal and Optical Testing of High Power LEDs.....100**
Márton C. Bein², János Hegedus¹, Gusztáv Hantos¹, Lajos Gaál², Gábor Farkas², Márta Rencz^{1,2}, András Poppe^{1,2}
¹Mentor, A Siemens Company, Hungary; ²Budapest University of Technology and Economics, Department of Electron Devices, Hungary
- 07 Nanoscale Thermal Imaging of Active Devices by Fluorescent SThM.....104**
Hung-Ju Lin¹, A. Assy¹, Etienne Lemaire², Danick Briand², Laurent Billot¹, Patrick Gredin³, Michel Mortier³, Lionel Aigouy¹
¹ESPCI-CNRS, France; ²EPFL, Institute of Microengineering, LMTS, Switzerland; ³Chimie ParisTech, CNRS, IRCP, France
- 08 Time Constant Spectra Based Fitting of Thermal Model Parameters.....108**
Tomasz Raszowski, Agnieszka Samson, Piotr Zajac, Tomasz Torzewicz, Artur Sobczak, Marcin Janicki, Mariusz Zubert, Andrzej Napieralski
Lodz University of Technology, Poland
- 09 An Investigation of Porous Structure Characteristics of Heat Pipes Made by Additive Manufacturing.....112**
Davoud Jafari, Wessel W. Wits, Bernard J. Geurts
University of Twente, The Netherlands

Poster Viewing Session

🕒 6.10 pm – 8.15 pm

Thursday, September 28, 2017

🕒 8:30 am – 5:40 pm

Thursday, September 28, 2017

Keynote II:

Development and Future Expectations of LED Lighting Systems

Wilbert IJzerman, Philips Lighting Research

Chair: Genevieve Martin, Philips Lighting

🕒 8.30 am – 9.15 am

➔ **Session 5:**
Solid State Lighting
🕒 9.15 am – 10.15 am

➔ **Session 6:**
Thermal Materials
🕒 10.50 am – 12.10 pm

➔ **Poster Introduction 2**
🕒 1.30 pm – 2.20 pm

➔ **Poster Viewing 2**
🕒 2.20 pm – 3.20 pm

➔ **Session 7:**
Electro/Thermal
🕒 3.20 pm – 4.40 pm

➔ **Session 8:**
Reliability
🕒 4.40 pm – 5.40 pm

Session 5:

Solid State Lighting

🕒 9.15 am – 10.15 am

➔ Chair: Thomas Zahner, OSRAM Opto Semiconductors GmbH

9.15 am Thermal Resistance and Temperature Distribution in Blue and White High-Power LED Arrays.....119

Anton Chernyakov¹, Andrew Aladov¹, Ilja Belov², Ivan Kalashnikov¹, Alexander Zakgeim¹

¹Submicron Heterostructures for Microelectronics Research and Engineering Center of RAS, Russian Federation; ²Jönköping University, Jönköping, Sweden

9.35 am Modulation Method for Measurement of Thermal Resistance of High-Power COB LEDs.....123

Vitaliy I. Smirnov¹, Viacheslav A. Sergeev², Andrey A. Gavrikov², Anton M. Shorin²

¹Ulyanovsk State Technical University, Russian Federation; ²Institute of Radioengineering and Electronics of Russian Academy of Science, Russian Federation

9.55 am Lifetime Iso-flux Control of LED based Light Sources.....127

János Hegedüs, Gusztáv Hantos, András Poppe

Budapest University of Technology and Economics, Hungary

Session 6:

Thermal Materials

🕒 10.50 am – 12.10 pm

➔ Chair: Bernhard Wunderle, TU Chemnitz

10.50 am Modification of Thermal Conductivity and Phonon Dispersion Relations by Means of Phononic Crystals.....132

Marianna Sledzinska¹, Alexandros El Sachat^{1,2}, J. Sebastian Reparaz¹, Markus R. Wagner¹, Francesc Alzina¹, Clivia M. Sotomayor Torres^{1,3}

¹Catalan Institute of Nanoscience and Nanotechnology (ICNP), CSIC and The Barcelona Institute of Science and Technology Campus UAB, Barcelona, Spain; ²Universitat Autònoma de Barcelona, Barcelona, Spain; ³ICREA - Institutio Catalana de Recerca i Estudis Avancats, Barcelona, Spain

11.10 am Application of Amorphous Diamond Materials to Provide a Reliable, Electrically Insulating, Thermal Interface for IC Devices for Electronics Applications in Harsh Environments.....136

Chris H. Walker, Eden T. Winlow

Diamond Hard Surfaces Ltd, United Kingdom

11.30 am Size Effects on the Thermal Conductivity of Nano Aerogels.....143

Jose Ordóñez, Younes Ezzahri, Karl Joulain

CNRS, France

11.50 am Thermal Conduction in Novel Isotropic Conductive Adhesive.....148

H. Kristiansen^{1,2}, K. Redford¹, S. Helland³, E. Kalland³, M. Abo Ras⁴, C. Grosse⁴, Bruno Hay⁵, L. Ramiandrisoa⁶, G. Davé⁶, S. Pettersen^{1,2}, N. Høglund¹; Séverine Gomès⁸

¹Conpart AS, Norway; ²Norwegian University of Science and Technology, Norway; ³Mosaic Solution AS, Norway; ⁴Berliner Nanotest und Design GmbH, Germany; ⁵Laboratoire National de Métrologie et d'Essais (LNE), Paris, France; ⁶National Center for Scientific Research (CNRS), Lyon, France

Poster Introduction 2

🕒 1.30 pm – 2.20 pm

➔ Chair: Genevieve Martin, Philips Lighting

01 Study on the Temperature-dependent Thermal Resistance Matrix of a Multi-chip LED-Matrix.....153

Lisa Mitterhuber, Stefan Defregger¹, Julien Magnien¹, Jödis Rosc¹, Franz Schrank², Stefan Hörth³, Lena Goullon⁴, Matthias Hutter⁴, Elke Kraker¹

¹Materials Center Leoben Forschungs GmbH, Leoben, Austria;

²Tridonic Jennersdorf GmbH, Jennersdorf, Austria; ³Häusermann GmbH,

Gars am Kamp, Austria; ⁴Fraunhofer-Institut für Zuverlässigkeit und

Mikrointegration IZM, Berlin, Germany

02 Experimental and Modelling Thermal Study of a 3D-stacked Silicon Based LEDs Array Concept.....158

Bertrand Chambion¹, Boris Bouillard¹, Adrien Gasse¹, Aurélie Vandeneynde¹, Nacer Ait-Mani¹, David Henry¹, Frédéric Mercier², Pamela Rueda³

¹Cea-Leti, Minatec Campus, France; ²Aledia SAS, France

03 An Investigation of Component Interaction and Analysis of Its Impact on Electro-thermal Behaviour in a Power Dense Boost Converter Topology.....163

Mohammad Shahjalal, Hua Lu, Christopher Bailey

University of Greenwich, United Kingdom

04 A Numerical Investigation into the Effect of Relative Humidity on Natural Convection Cooling of Electronics.....167

Parizad Shojaei Nasirabadi^{1,2}, Jesper H. Hattel¹

¹Technical University of Denmark, Denmark; ²Georgia Institute of Technology, United States of America

05 Thermal Interaction of Dissipating Devices in Power Applications.....171

Ferdinand Sluijs

NXP Semiconductors, The Netherlands

06 Co-Design/Simulation of Flip-Chip Assembly for High Voltage IGBT Packages.....175

Chris Bailey

University of Greenwich, United Kingdom

07 Thermal Conductivity of 2D and 3D Silicon Nanowire Meshes.....N/A

Maxime Verdier, David Lacroix, Konstantinos Termentzidis

LEMTA, UMR 7563 CNRS and University of Lorraine, Vandœuvre-lès-Nancy, France

08 “TIMAwave” an Innovative Test Platform for Thermal Diffusivity Measurements of Solid Materials at High Temperature.....180

Mohamad Abo Ras¹, Dan Ralf Wargulski¹, Daniel May^{1,2}, Bernhard Wunderle²

¹Berliner Nanotest und Design GmbH, Germany; ²Technische Universität Chemnitz, Germany

Poster Viewing 2

🕒 2:20 pm – 3:20 pm

Session 7: Electro/Thermal

🕒 3.20 pm – 4.40 pm

→ Chair: Andrzej Napieralski, Technical University of Lodz

3.20 pm Fast Electro-thermal Simulation of Large Area OLEDs in Natural Convection Environment.....184

László Pohl, Zsolt Kohári, András Poppe

Budapest University of Technology and Economics, Hungary

3.40 pm Efficient Modelling Approach for Transient Coupled Electro-Thermal Simulation on the Example of a Chip-on-Board Application.....189

Ralph Schacht¹, Sven Rzepka²

¹Brandenburgische Technische Universität Cottbus-Senftenberg, Germany; ²Fraunhofer Institute ENAS, Chemnitz, Germany

4.00 pm Adaptive Co-Simulation of Functional-Thermal Behaviour of Integrated Circuits.....195

Lázár Jani, András Poppe

Budapest University of Technology and Economics, Hungary

4.20 pm Extension of Standard SPICE SiGe HBT Models in the Cryogenic Temperature Range.....203

Konstantin O. Petrosyants^{1,2}, Oleg V. Dvornikov³, Nikolay N. Prokopenko⁴, Maxim V. Kozhukhov⁵

¹National Research University Higher School of Economics, Moscow, Russian Federation; ²Institute for Design Problems in Microelectronics of RAS, Moscow, Russian Federation; ³JSC «MNIP», Minsk, Belarus; ⁴Don State Technical University, Rostov-On-Don, Russian Federation; ⁵JC VNIEM Corporation, Moscow, Russian Federation

Session 8: Reliability

🕒 4.40 pm – 5.40 pm

→ Chair: Ari Glezer, Georgia Institute of Technology

4.40 pm A New Analytical Approach to the Geometry of a Compressed Liquid Bump.....208

Co van Veen¹, Wendy Luiten²

¹Mat-Tech B.V., DR Son, The Netherlands; ²WLC, Riethoven, The Netherlands

5.00 pm Failure Analysis of S-Parameter in N-MOSFET Devices after Thermal Life Tests.....214

Mohamed Ali Belaid¹, A.M. Nahhas², M. Masmoudi³

¹LATIS-ENISo, Sousse University, Tunisia; ²Umm Al-Qura University, Makkah, Saudi Arabia; ³GPM-UMR CNRS, University of Rouen, France

5.20 pm Computer Simulation of the Reliability of Wire Bonds and Ribbon Bonds in Power Electronics Modules.....219

Kenneth Chimezie Nwanoro, Hua Lu, Chunyan Yin, Chris Bailey

University of Greenwich, Greenwich, United Kingdom

Friday, September 29, 2017

Keynote III:

60 Years of Electronics Cooling: 1965-2025

Clemens Lasance, Emeritus Scientist at Philips Research

Chair: András Poppe, Budapest University of Technology and Economics

🕒 8.30 am – 9.15 am

Presentation iTHERM

🕒 9.15 am – 9.30 am

→ Session 9A: Thermal Management

→ Session 9B: European Projects on Measurement Technologies

🕒 9.30 am – 10.30 am

→ Session 10A: Novel Cooling /Heatpipes/Additive Manufacturing

→ Session 10B: European Projects on Modelling and Simulation

🕒 11.00 am – 12.20 pm

→ Session 11A: Modelling and Simulation II

→ Session 11B: European Projects on LED

🕒 12.20 pm – 1.20 pm

→ Session 12: Thermal Measurement II

🕒 2.20 pm – 3.40 pm

Friday, September 29, 2017

🕒 9.30 am – 11.00 pm

Session 9A: Thermal Management

🕒 9.30 am – 10.30 am

→ Chair: Vadim Tsoi, Huawei Technologies Sweden AB

9.30 am Thermal Modelling to Optimize Design in Mobile Charging Applications.....225

Ferdinand Sluijs
NXP Semiconductors, The Netherlands

9.50 am Practical Thermal Control by Thermo-Electric Actuators.....230

Rob van Gils
Royal Philips, The Netherlands

10.10 am Carbon-based Patterned Heat Spreaders for Thermal Mitigation of Wire Bonding Packages.....236

Jean-Philippe Colonna¹, Rafael Prieto^{1,2,3}, Perceval Coudrain², Yves Hallez², Didier Campos², Olivier Le-Briz², Rémi Franiatte¹, Catherine Brunet-Manquat¹, Christian Chancel¹, Venceslass Rat¹
¹CEA, LETI, MINATEC Campus; ²STMicroelectronics, France; ³CNRS G2Elab, Grenoble, France

Session 9B: European Projects on Measurement Technologies

🕒 9.30 am – 10.30 am

→ Chair: P.-Olivier Chapuis, CNRS - INSA Lyon

9.30 am QUANTIHEAT Project: Main Results and Products.....242

P.-Olivier Chapuis¹, Séverine Gomès²
¹CNRS - INSA, Lyon, France; ²Centre d'Energétique et de Thermique de Lyon, France

9.50 am Quantitative Measurement using Resistive SThM Micro and Nanoprobes.....N/A

Séverine Gomès, Eloïse Guen, David Renahy, P.-Olivier Chapuis
University of Lyon, CNRS, INSA-Lyon, Villeurbanne, France

10.10 pm Scanning Thermal Microscopy: Wollaston Probe/Sample Heat Transfer Modeling.....N/A

Patricia Ai Alam, Rakibul Islam, Dheeraj Pratap, Jaona Randrianalisoa, Nathalie Trannoy
URCA/GRESPI, Reims University, France

Friday, September 29, 2017

🕒 11.00 pm – 12.20 pm

Session 10A: Novel Cooling /Heatpipes/Additive Manufacturing

🕒 11.00 pm – 12.20 pm

→ Chair: Wessel W. Wits, University of Twente

11.00 pm Enhancement of Forced Convection Heat Transfer Using Aeroelastically Fluttering Reeds.....248

Thomas Crittenden, Sourabh Jha, Ari Glezer
Georgia Institute of Technology, United States of America

11.20 pm Experimental Spray Cooling Studies with FC-72 and FC-84 to Comprehend the Validity of Volumetric Flux Model (VFM).....254

Çagri Balıkcı¹, İlker Tari²
¹ASELSAN, Turkey; ²Middle East Technical University, Turkey

11.40 pm Novel Method for Fast FEM Simulation of Chips with Integrated Microchannel Cooling.....260

Piotr Zajac, Andrzej Napieralski
Lodz University of Technology, Poland

12.00 pm An Experimental Study towards the Practical Application of Closed-loop Flat-plate Pulsating Heat Pipes.....267

Gerben Groeneveld¹, Henk Jan van Gerner², Wessel W. Wits¹
¹University of Twente, The Netherlands; ²National Aerospace Center (NLR), The Netherlands

Session 10B: European Projects on Modelling and Simulation

🕒 11.00 pm – 12.20 pm

→ Chair: Robin Bornoff, Mentor, A Siemens Business

11.00 pm Multiscale Simulation of Heat Transport in Materials Subjected to Localized Heat Sources.....N/A

Thi Thu Trang Nghiem^{1,2}, Nathalie Trannoy¹, P.-Olivier Chapuis², Jaona Randrianalisoa¹
¹University of Reims Champagne-Ardenne, France; ²CETHIL, Villeurbanne, Lyon-Tech; France

11.20 pm Microfluidic Cell Cooling System for Electronics.....273

Gerard Laguna¹, Hassan Azarkish², Montse Vilarrubí¹, Manel Ibañez¹, Joan Rosell¹, Yina Betancourt¹, Josep Illa¹, Louis-Michel Collin², Jérôme Barrau¹, Luc Fréchette², Perceval Coudrain³, Guillaume Savelli⁴
¹Universitat de Lleida, Spain; ²Université de Sherbrooke, Canada; ³STMicroelectronics, France; ⁴CEA - Liten, France

11.40 pm Dynamic Compact Thermal Model Extraction for LED Packages Using Model Order Reduction Techniques.....277

Sangye Lungten¹, Wil H.A. Schilders¹, Joseph M.L. Maubach¹, Robin Bornoff², James Dyson², Matt Warner²
¹Eindhoven University of Technology, The Netherlands; ²Mentor, A Siemens Business, Hampton Court, UK

12.00 pm Low Order Compact Model Development for LED Package Thermal Investigation.....283

Márton Németh, András Poppe
Budapest University of Technology and Economics, Hungary

Friday, September 29, 2017

🕒 12.20 pm – 1.20pm

Session 11A: Modelling and Simulation II

🕒 12.20 pm – 1.20 pm

➔ Chair: John Parry, Mentor, A Siemens Business

12.20 pm The Scope of Applicability of DPL Model to the Heat Transfer in Integrated Circuits.....288

Mariusz Zubert, Tomasz Raszkowski, Agnieszka Samson, Marcin Janicki, Piotr Zajac
DMCS, Lodz University of Technology, Poland

12.40 pm Manufacturing and Characterisation of MEMS Test Nanostructures.....294

Grzegorz Jablonski¹, Pawel Janus¹, Piotr Pietrzak¹, Tomasz Torzewicz¹, Artur Sobczak¹, Marcin Janicki¹, Andrzej Napieralski¹, Andrzej Sierakowski², Anna Brzezinska², Piotr Prokaryn²
¹*Lodz University of Technology, Poland;* ²*Institute of Electron Technology, Warsaw, Poland*

1.00 pm Thermal Behaviour Modeling of Enzymatic Reactions in Flow-through Microchambers.....299

Péter Pálovics, Márta Rencz
Budapest University of Technology and Economics, Hungary

Session 11B: European Projects on LED

🕒 12.20 pm – 1.20pm

➔ Chair: Genevieve Martin, Philips Lighting

12.20 pm Assessment of Isothermal Electro-Optical-Thermal Measurement Procedures for LEDs.....306

Grigory A. Onushkin¹, Karel Joop Bosschaart¹, Joan Yu¹, Henk Jan van Aalderen¹, Julien Joly², Genevieve Marin¹, András Poppe³
¹*Philips Lighting, The Netherlands;* ²*Philips Lighting, Miribel, France;* ³*Budapest University of Technology and Economics, Hungary*

12.40 pm Delphi4LED: LED Measurements And Variability Analysis.....312

Thomas Merelle¹, Alessandro Di Buccianico², Josephine K. Sari², Dan Breton³
¹*Pi lighting, Switzerland;* ²*Eindhoven University of Technology, The Netherlands* ³*PISEO, Vénissieux, France*

1.00 pm K-factor Calibration Issues of High Power LEDs.....318

Gusztav Hantos, János Hegedüs
Budapest University of Technology and Economics, Hungary

Friday, September 29, 2017

🕒 2.20 pm – 4:15pm

Session 12: Thermal Measurement II

🕒 2.20 pm – 3.40 pm

➔ Chair: Mohamad Abo Ras, Berliner Nanotest und Design GmbH

2.20 pm In-situ Transient Testing of Thermal Interface Sheets and Metal Core Boards in Power Switch Assemblies.....324

Gabor Farkas¹, Juergen Zettner², Zoltan Sarkany¹, Marta Rencz²
¹*Mentor, A Siemens Business, Budapest, Hungary;* ²*Budapest University of Technology and Economics, Hungary;* ³*Siemens, Nürnberg, Germany*

2.40 pm Design and Realization of Characterization Demonstrator to Investigate Thermal Performance of Vertically-aligned Carbon Nanotubes TIM for Avionics and Aerospace Applications.....330

Mohamad Abo Ras¹, Tobias von Essen¹, Julien Fortel², Pranav Panchal¹, Laurent Divay³, Ana Borta-Boyon³, Daniel May^{1,4}, Christian Chandra Darmawan⁵, Majid Kabiri Samani⁶, Bernhard Wunderle⁴, Afshin Ziaei³
¹*Berliner Nanotest und Design GmbH, Germany;* ²*Thales Microelectronics, France;* ³*Thales Research and Technology, France;* ⁴*Technische Universität Chemnitz, Chemnitz, Germany;* ⁵*SHT Smart High Tech AB, Sweden;* ⁶*Chalmers University of Technology, Sweden*

3.00 pm Calibration of Transient FE Simulation: Improvement of Post-Processing and Simulation Automation.....336

Siddharth Saparia¹, Gordon Elger¹, E Liu¹, Thomas Zahner², Sebastian Besold², Wolfgang Kalb², Sanchit Tandon²
¹*Technische Hochschule Ingolstadt, Germany;* ²*OSRAM Opto Semiconductors GmbH, Regensburg, Germany*

3.20 pm Thermopower Characterization of InSb Nanowires Using Thermorefectance.....342

Ruben Chavez¹, Daniel Vakulov¹, Sasa Gazibegovic^{1,3}, Dustin Kendig⁴, Andrew A. O. Tay⁴, Ali Shakouri^{2,4}, Erik P. A. M. Bakkers²
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Award Ceremony & Closing Remarks

🕒 3.50 pm – 4.15 pm